506322468 10/27/2020

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
CHIA-YI LEE	10/21/2020
KUAN-YU SHIH	10/21/2020
KA-UN CHAN	10/21/2020

RECEIVING PARTY DATA

Name:	REALTEK SEMICONDUCTOR CORPORATION	
Street Address:	NO. 2, INNOVATION ROAD II, HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	Taiwan ROC	
Postal Code:	300	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	17080890	

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	16313-286	
NAME OF SUBMITTER:	JUSTIN KING	
SIGNATURE:	/Justin King/	
DATE SIGNED: 10/27/2020		

Total Attachments: 2 source=a#page1.tif source=a#page2.tif

PATENT 506322468 REEL: 054172 FRAME: 0422

ASSIGNMENT

WHEREAS, I(we), CHIA-YI LEE, KUAN-YU SHIH and KA-UN CHAN whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled.

TRANSCEIVER DEVICE

(hereinafter referred to as the INVENTION) for which an a is executed on even date herewith unless at least one of to United States Design Patent was executed on:		etters Patent /Utility Patent
☐ filed on: Serial No.: ☐ established by PCT International Patent Applica United States of America ☐ issued on as U.S. Patent N		designating the
WHEREAS, REALTEK SEMICONDUCTOR CORP Innovation Road II, Hsinchu Science Park, Hsinchu is desirous of acquiring the entire right, title and interest possessions;	ORATION whose post office a 300, Taiwan (R.O.C.) hereinaf	fter referred to as ASSIGNEE,
NOW, THEREFORE, for good and valuable considerable ASSIGNOR, by these presents do sell, assign and transferand to said INVENTION and application throughout the Patent granted on any division, continuation, continuation terms for which the same may be granted, including all processing the same of the process of the same of the process of the same of the process of	er unto said ASSIGNEE, the enti e United States of America, in on-in-part and reissue of said ap	ire right, title, and interest in including any and all Letters oplication for the full term or
ASSIGNOR further covenants that no assignments, or entered into which would conflict with this Assignme		ce has been or will be made
ALSO, ASSIGNOR hereby agrees to execute any doc filing, prosecution and maintenance of said application said INVENTION, including additional documents that m said INVENTION, all without further consideration. ASSIGNEE'S expense, to identify and communicate to Assignee's expense, to identify and communicate to Assignee in Invention that are within Assignor's ptestimony on behalf of Assignee that lawfully may maintenance, litigation and defense of any patent appinstrument. Assignor's obligations under this insadministrators and other legal representatives.	or any other patent application as the required to affirm the rissingner at Assigner's request possession or control, and to probe required of Assignor in plication or patent encompasses.	n(s) in the United States for ights of ASSIGNEE in and to further consideration and at a documents and information rovide further assurances and respect of the prosecution, ed within the terms of this
ALSO, ASSIGNOR hereby authorizes and requests t and all Letters Patent referred to above to ASSIGNEE, as the same, for ASSIGNEE's sole use and behoof; and for t successors, to the full end of the term for which such I same would have been held by ASSIGNOR had this assign	the ASSIGNEE of the entire rigithe use and behoof of ASSIGNE Letters Patent may be granted,	ht, title and interest in and to E'S legal representatives and
ASSIGNOR NAME	Address	
CHIA-YI LEE	No. 2, Innovation Road I Hsinchu 300, Taiwan (R.	I, Hsinchu Science Park, O.C.)
Signature of Assignor	Date of Signature	
Chia-yi Lee	October 21, 202	0
Name of Witness (optional)	Name of Witness (optional)	
Signature of Witness (optional)	Signature of Witness (Optional)	

PATENT REEL: 054172 FRAME: 0423

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ASSIGNOR NAME	Address	
KUAN-YU SHIH	No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)	
Signature of Assignor Kuan - Tu Shih	Date of Signature October 21, 2020	
Name of Witness (optional)	Name of Witness (optional)	
Signature of Witness (optional)	Signature of Witness (Optional)	
ASSIGNOR NAME	Address	
KA-UN CHAN	No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)	
Signature of Assignor Ka-lu Kan	Date of Signature October 21, 2020	
Name of Witness (optional)	Name of Witness (optional)	
Signature of Witness (optional)	Signature of Witness (Optional)	

PATENT REEL: 054172 FRAME: 0424

RECORDED: 10/27/2020